# **Question Paper Code: 46404**

### B.E. / B.Tech. DEGREE EXAMINATION, NOV 2019

Sixth Semester

## **Electronics and Communication Engineering**

#### 14UEC604-VLSI DESIGN

(Regulation 2014)

Duration: Three hours		Maximum: 100 Marks
	Answer ALL Questions	

(Smith chart may be permitted)

PART A -  $(10 \times 1 = 10 \text{ Marks})$ 

- VLSI technology uses \_\_\_\_\_\_to form integrated circuit.
   (a) Transistors (b) Switches (c) Diodes (d) Buffers
- 2. The difficulty in achieving high doping concentration leads to
  - (a) Error in concentration

(b) Error in variation

(c) Error in doping

- (d) Distribution
- 3. In accordance to the scaling technology, the total delay of the logic circuit depends on
  - (a) The capacitor to be charged
  - (b) The voltage through which capacitance must be charged
  - (c) Available current
  - (d) All of the above

4.	In CMOS circuits, which type of power dissipation occurs due to switching of transcurrent & discharging of load capacitance?			
	(a) Static dissipati	on	(b) Dynamic o	dissipation
	(c) Both a and b		(d) None of the	e above
5.	The output of latches (a) The trigger put (b) Any pulse give (c) They don't get (d) None of the M	lse is given to cha n to go into previ any pulse more	ange the state	
6.	The sequential circuit is	s also called		
	(a) Flip-flop	(b) Latch	(c) Strobe	(d) None of the Mentioned
7.	Boundary scan test is	used to test		
	(a) Pins	(b) Multiplier	rs (c) Boards	(d) wires
8.	CMOS domino logic o	occupies		
	(a) Smaller area		(b) Larger area	
9.	(c) Both of the mer Test Benches procedu		(d) None of the	e mentioned
	(a) Smaller design	l	(b) Larger desi	gn
10	(c) Complicated  D. Blocking & Non block	king assignment i	(d) None of the	mentioned
<ul><li>(a) =statement &amp; ≤ statement</li><li>(c) Statement</li></ul>			(b) ≤ statement (d) ≥ statement & =statement	
11	. What is Body effect an		5 x 2 = 10 Marks) h modulation?	
12	. Define design margin.			
13	3. Draw the pseudo nmo	s inverter.		
14	. What is stuck – at faul	t?		
15	6. What is the structural	gate-level modeli	ng?	

## PART - C (5 x 16 = 80 Marks)

16. (a) Explain layout design rules in detail.	(16)					
Or						
(b) Explain in detail about region and modes of	operations in MOSFET. (16)					
17.(a) Explain in detail about delay estimation, log example.  Or	(16)					
(b) Explain the static and dynamic power dissip diagrams and expressions.	(16)					
18. (a) Explain in detail: (i) Conventional CMOS	Latch (ii) Conventional CMOS Flip flop. (16)					
Or						
(b) Explain in detail about sequencing dynamic	c circuits and synchronizers. (16)					
19. (a) What are the various testing methods to circuit?	be considered while designing a VLSI (16)					
Or						
(b) Explain in detail about silicon debug princi	ples. (16)					
20. (a) Explain the concept involved in structura description for Decoder and parity encoder.						
Or						
(b) Explain the looping statements and procedu	aral assignments in VERILOG HDL. (16)					